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Intel - 10AX090N1F45E1SG Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Active
Number of LABs/CLBs	339620
Number of Logic Elements/Cells	900000
Total RAM Bits	59234304
Number of I/O	768
Number of Gates	-
Voltage - Supply	0.87V ~ 0.98V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FCBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10ax090n1f45e1sg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Intel[®] Arria[®] 10 Device Overview

The Intel[®] Arria[®] 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Market	Applications
Wireless	Channel and switch cards in remote radio headsMobile backhaul
Wireline	 40G/100G muxponders and transponders 100G line cards Bridging Aggregation
Broadcast	 Studio switches Servers and transport Videoconferencing Professional audio and video
Computing and Storage	Flash cacheCloud computing serversServer acceleration
Medical	Diagnostic scannersDiagnostic imaging
Military	 Missile guidance and control Radar Electronic warfare Secure communications

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

Related Information

Intel Arria 10 Device Handbook: Known Issues Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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Feature	Description	
Low-power serial transceivers	 Continuous operating range: Intel Arria 10 GX—1 Gbps to 17.4 Gbps Intel Arria 10 GT—1 Gbps to 25.8 Gbps Backplane support: Intel Arria 10 GX—up to 12.5 Intel Arria 10 GT—up to 12.5 Extended range down to 125 Mbps with oversampling ATX transmit PLLs with user-configurable fractional synthesis capability Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module Adaptive linear and decision feedback equalization Transmitter pre-emphasis and de-emphasis Dynamic partial reconfiguration of individual transceiver channels 	
HPS (Intel Arria 10 SX devices only)	Processor and system • Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability • 256 KB on-chip RAM and 64 KB on-chip ROM • System peripherals—general-purpose timers, watchdog timers, di memory access (DMA) controller, FPGA configuration manager, ar clock and reset managers • Security features—anti-tamper, secure boot, Advanced Encryptior Standard (AES) and authentication (SHA) • ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage	nd n
	 External interfaces Hard memory interface—Hard memory controller (2,400 Mbps DE and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) fl controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller Communication interface—10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os) 	lash
	Interconnects to core • High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write • HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to iss transactions to slaves in the HPS, and vice versa • Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port • FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller	
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investment Enhanced 256-bit advanced encryption standard (AES) design security with authentication Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3 	
	continue	d

 $^{^{(2)}\,}$ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Maximum Resources

Table 5.Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX
270, GX 320, and GX 480)

Reso	ource			Product Line		
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements	(LE) (K)	160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb) M20K MLAB		8,800	11,740	15,000	17,820	28,620
		1,050	1,690	2,452	2,727	4,164
Variable-precisi	ariable-precision DSP Block		192	830 985		1,368
18 x 19 Multipli	x 19 Multiplier		384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Trans	sceiver	12	12	24	24	36
GPIO ⁽³⁾		288	288	384	384	492
LVDS Pair ⁽⁴⁾		120	120	168	168	222
PCIe Hard IP Bl	ock	1	1	2	2	2
Hard Memory C	ontroller	6	6	8	8	12

⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.



Table 6.Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line	
		GX 570	GX 660	GX 900	GX 1150
Logic Elements	s (LE) (K)	570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precis	sion DSP Block	1,523	1,687	1,518	1,518
18 x 19 Multip	lier	3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Trai	nsceiver	48	48	96	96
GPIO ⁽³⁾		696	696	768	768
LVDS Pair ⁽⁴⁾		324	324	384	384
PCIe Hard IP E	Block	2	2	4	4
Hard Memory	Controller	16	16	16	16

Package Plan

Table 7.Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)				F27 mm × 27 n 72-pin FBG/		F29 (29 mm × 29 mm, 780-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O LVDS I/O XCV			3 V I/O	LVDS I/O	XCVR	
GX 160	48	192	6	48	192	12	48	240	12	
GX 220	48	192	6	48	192	12	48	240	12	
GX 270	-	-	_	48	192	12	48	312	12	
GX 320	-	-	_	48	192	12	48	312	12	
GX 480	_	_	_	_	_	_	48	312	12	



Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)			F35 (35 mm × 35 mm, 1152-pin FBGA)			KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	_	_	_	_	-	-
GX 320	48	336	24	48	336	24	_	-	_	_	-	-
GX 480	48	444	24	48	348	36	_	-	-	_	-	-
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	-	504	24	-	-	-	_	-	-	_	600	48
GX 1150	-	504	24	-	-	-	_	-	-	_	600	48

Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)			NF45 (45 mm × 45 mm) 1932-pin FBGA)			SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR									
GX 900	_	342	66	_	768	48	_	624	72	_	480	96
GX 1150	_	342	66	_	768	48	_	624	72	_	480	96

Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 GT

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



ES : Engineering sample

RoHS

FPGA Fabric

Speed Grade

1 (fastest)

2 3

G : RoHS6 N : RoHS5 Contact Intel P : Leaded for availability

Available Options

Family Variant

090 : 900K logic elements 115 : 1,150K logic elements

25.8 Gbps transceivers

Transceiver

1 (fastest)

2

Speed Grade

T : GT variant

Logic Density



Package Code

45 : 1,932 pins, 45 mm x 45 mm

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices



Maximum Resources

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	urce	Produ	ct Line
		GT 900	GT 1150
Logic Elements (LE) (K)		900	1,150
ALM		339,620	427,200
Register		1,358,480	1,708,800
Memory (Kb)	M20K	48,460	54,260
	MLAB	9,386	12,984
Variable-precision DSP Block		1,518	1,518
18 x 19 Multiplier		3,036	3,036
18 x 19 Multiplier PLL	Fractional Synthesis	32	32
	I/O	16	16
Transceiver	17.4 Gbps	72 (5)	72 ⁽⁵⁾
	25.8 Gbps	6	6
GPIO ⁽⁶⁾		624	624
LVDS Pair ⁽⁷⁾		312	312
PCIe Hard IP Block		4	4
Hard Memory Controller		16	16

Related Information

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

Package Plan

Table 11.Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)						
	3 V I/O	LVDS I/O	XCVR				
GT 900	—	624	72				
GT 1150	_	624	72				

⁽⁵⁾ If all 6 GT channels are in use, 12 of the GX channels are not usable.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁷⁾ Each LVDS I/O pair can be used as differential input or output.



Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb) M20K		8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB		1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multiplier		312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO ⁽⁸⁾		288	288	384	384	492	696	696
LVDS Pair ⁽⁹⁾		120	120	168	168	174	324	324
PCIe Hard IP Block		1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-As Processor	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Package Plan

Table 13.Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
SX 160	48	144	6	48	192	12	48	240	12	_	-	-	
SX 220	48	144	6	48	192	12	48	240	12	_	-	-	
SX 270	-	-	_	48	192	12	48	312	12	48	336	24	
SX 320	-	-	_	48	192	12	48	312	12	48	336	24	
			continued										

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use
 memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to
 banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
 - Package Product Variant Line U19 F27 KF40 NF40 RF40 NF45 SF45 UF45 F29 F34 F35 GX 160 GX 220 GX 270 GX 320 Intel® Arria® 10 GX GX 480 GX 570 GX 660 GX 900 GX 1150 GT 900 Intel Arria 10 GT GT 1150 SX 160 SX 220 SX 270 Intel Arria 10 SX SX 320 SX 480 SX 570 SX 660
- Some migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line Variable- precision DSP Block			put and Output ons Operator	18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode	Summed with 36 bit Input
AIntel Arria 10 GX	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	GT 900	1,518	3,036	1,518	1,518	1,518
GT	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



Variant F	Product Line	precision		put and Output ns Operator	18 x 19 Multiplier	18 x 18 Multiplier
		DSP Block	18 x 19 Multiplier	27 x 27 Multiplier	Adder Sum Mode	Adder Summed with 36 bit Input
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single- Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating- Point Operations per Second (GFLOPs)
Intel Arria 10 GX	GX 160	156	156	156	156	140
GA	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	GT 900	1,518	1,518	1,518	1,518	1,366
GT	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	SX 160	156	156	156	156	140
SX	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Intel Arria 10 Devices

	Product	M2	:0K	ML	AB	Total RAM Bit
Variant	Line	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408

Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices



Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	-	533
	Quarter rate	_	800

Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 (11)	Quarter rate	1,200
QDR IV SRAM ⁽¹¹⁾	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

⁽¹¹⁾ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



PCS	Description
Standard PCS	 Operates at a data rate up to 12 Gbps Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.
Enhanced PCS	 Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA Handles data transfer to and from the FPGA fabric Handles data transfer internally to and from the PMA Provides frequency compensation Performs channel bonding for multi-channel low skew applications
PCIe Gen3 PCS	 Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates Provides support for PIPE 3.0 features Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed

Related Information

- PCIe Gen1, Gen2, and Gen3 Hard IP on page 26
- Interlaken Support on page 26
- 10 Gbps Ethernet Support on page 26

PCS Protocol Support

This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS
10GBASE-R	10.3125	Native PHY	Enhanced PCS
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS
10G SDI	10.692	Native PHY	Enhanced PCS
			continued



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 ⁽¹²⁾ to 2.97	Native PHY	Standard PCS

Related Information

Intel Arria 10 Transceiver PHY User Guide

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

⁽¹²⁾ The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux*, VxWorks*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
 - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
 - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

Enhanced Configuration and Configuration via Protocol

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security ⁽¹ 4)	Partial Reconfiguration (15)	Remote System Update
JTAG	1 bit	33	33	_	_	Yes ⁽¹⁶⁾	-
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes ⁽¹⁶⁾	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes ⁽¹⁶⁾	Parallel Flash Loader (PFL) IP core
						со	ntinued

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁶⁾ Partial configuration can be performed only when it is configured as internal host.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V_{CC} while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- Low Static Power Options—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

Document Revision History for Intel Arria 10 Device Overview

Document Version	Changes
2018.04.09	Updated the lowest V_{CC} from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	• Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.
		 Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in <i>Memory Standards Supported by the Soft</i> <i>Memory Controller</i> table.
		Updated transceiver backplane capability to 12.5 Gbps.
		• Removed transceiver speed grade 5 in <i>Sample Ordering Core and Available Options for Intel Arria 10 GX Devices</i> figure.
	1	continued

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September 2017 July 2017 July 2017 May 2017 May 2017 March 2017	2017.09.20 2017.07.13 2017.07.06 2017.05.08	 Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from <i>Sample Ordering Core and Available Options for Intel Arria 10 GT Devices</i> figure. Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps. Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from <i>PMA Features of the Transceivers in Intel Arria 10 Devices</i> table. Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family. Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants.
July 2017 July 2017 May 2017	2017.07.13 2017.07.06 2017.05.08	 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family. Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration
July 2017 May 2017	2017.07.06 2017.05.08	 available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family. Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration
May 2017	2017.05.08	 Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration
		Updated the vertical migration table to remove vertical migration
March 2017		Removed all "Preliminary" marks.
	2017.03.15	 Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices. Rebranded as Intel.
October 2016	2016.10.31	 Removed package F36 from Intel Arria 10 GX devices. Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.
May 2016	2016.05.02	 Updated the FPGA Configuration and HPS Booting topic. Remove V_{CC} PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices. Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA. Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.
February 2016	2016.02.11	 Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally. Revised the state for Core clock networks in the Summary of Features topic. Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table. Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table. Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table. Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure. Changed the transceiver parameters in the "Low Power Serial Transceivers" section. Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table. Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure. Changed the datarates for GT devices in the "PMA Features" section. Changed the datarates for GT devices in the "PCS Features" section.